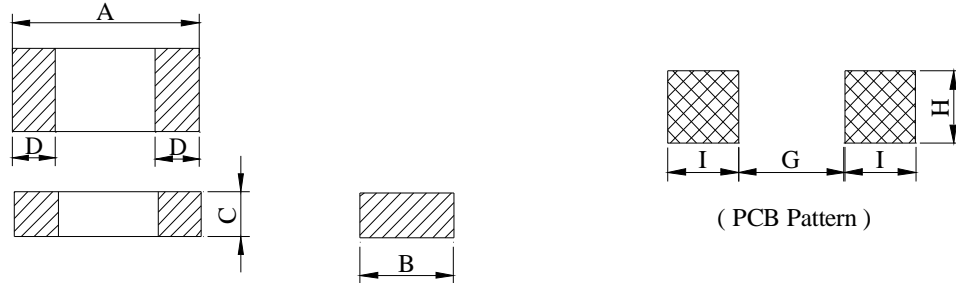


SPECIFICATION FOR APPROVAL

PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



Unit : m/m

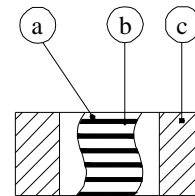
Series	A	B	C	D	G	H	I
MB2029	2.0±0.2	1.2±0.2	0.9±0.2	0.5±0.3	1.0	1.0	1.0
MB1608	1.6±0.2	0.8±0.2	0.8±0.2	0.3±0.2	0.7	0.7	0.7

II . SCHEMATIC DIAGRAM :



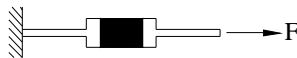
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

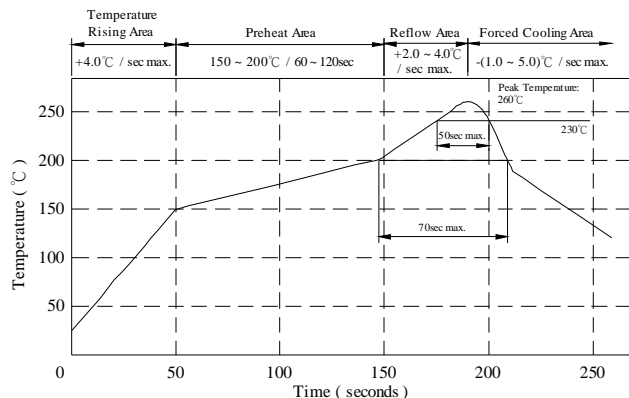
- a . Storage Conditions :
Electrical Performance temp : -55°C ~ +125°C
Terminal Solderability & Packages Material temp : -10°C ~ +40°C and RH 70% max.
- b . Operating temp. : -55°C ---- +125°C
- c . Terminal strength :



Type	F (kgf)	Time (sec)
MB2029	0.6	30±5
MB1608	0.5	

- d . Solderability : Preheat : 150±25°C for 60 seconds
Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
Solder temp. : 260±5°C
Flux : Rosin
Dip time : 4±1 seconds

Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.



SPECIFICATION FOR APPROVAL

REF : 20100706-C

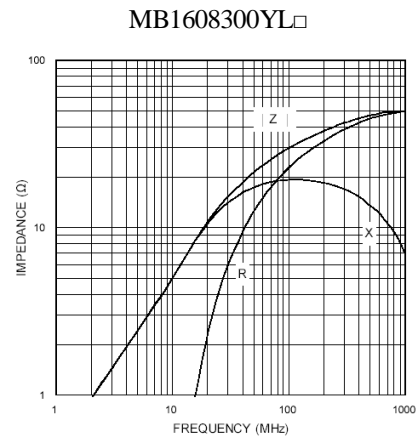
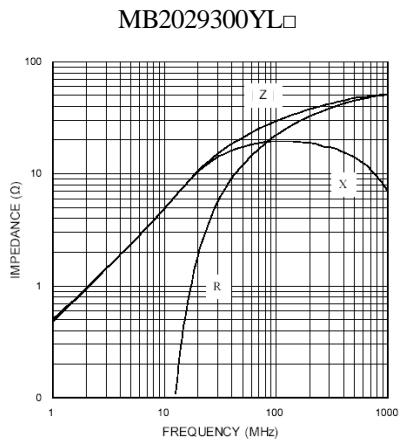
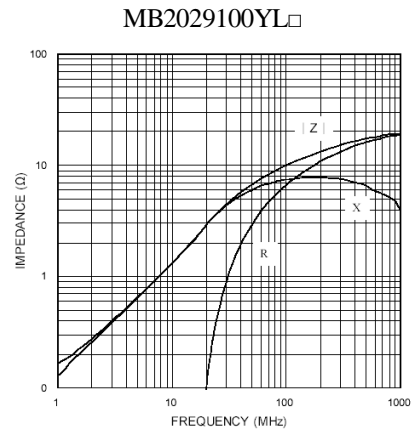
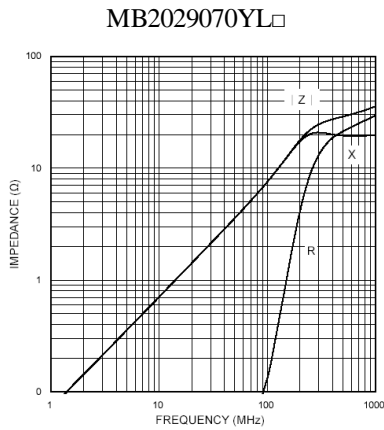
PAGE: 2

PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω) at 100MHz	RDC (m Ω) max.	IDC (A) max.
MB2029070YL□ - □□□	7 \pm 25%	30	3.0
MB2029100YL□ - □□□	10 \pm 25%	30	3.0
MB2029300YL□ - □□□	30 \pm 25%	25	3.0
MB1608300YL□ - □□□	30 \pm 25%	60	1.0

- 1). □ : Paclaging Information... **A** : Bulk **B** : Taping Reel
 2). "- □□□ " : Reference code



AR-001A

SPECIFICATION FOR APPROVAL

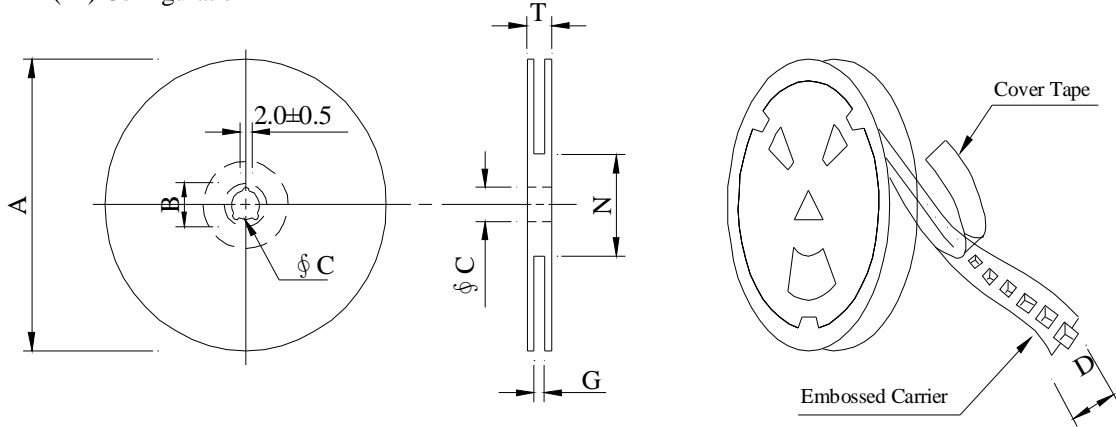
REF : 20100706-C

PAGE: 3

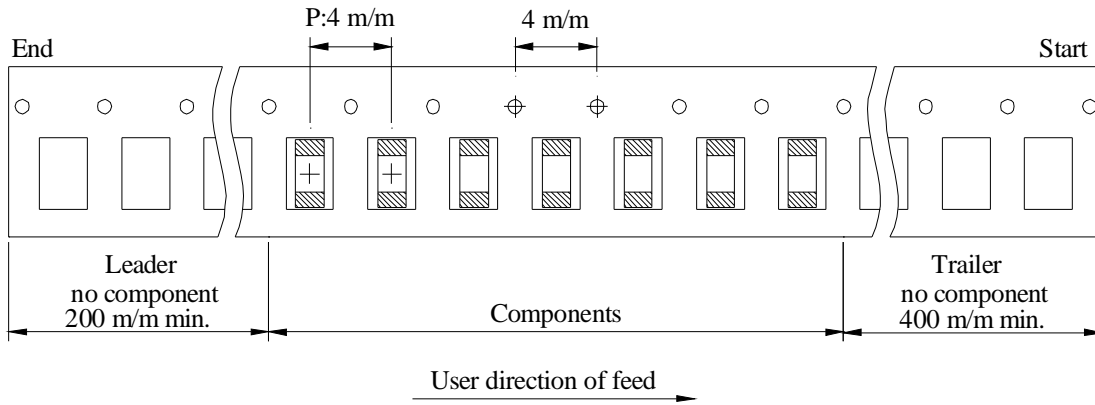
PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

VI . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Cartion		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(kpcs)	G.W. (Kg)	Size (cm)
MB2029	4,000	120	07 - 08	200	8.5	41 x 39 x 22
MB1608	4,000	90	07 - 08	200	7.0	41 x 39 x 22

SPECIFICATION FOR APPROVAL

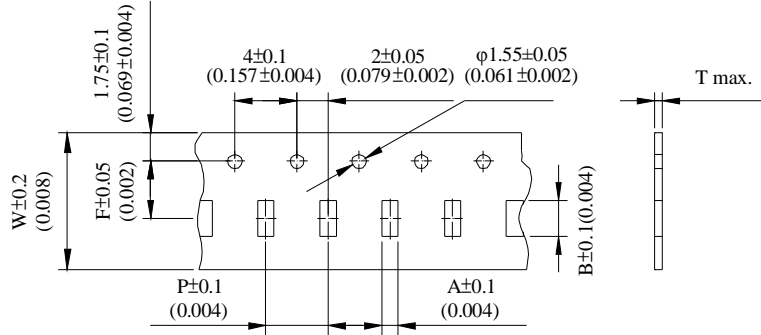
REF : 20100706-C

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PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

(4) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MB2029	1.50	2.30	3.50	4.0	1.10	8.0	1
MB1608	1.05	1.85	3.50	4.0	1.10	8.0	1

